

LNJ947W8CRA

High Bright Surface Mounting Chip LED

1005 Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	40	mW
Forward current	I_F	10	mA
Pulse forward current *	I_{FP}	40	mA
Reverse voltage	V_R	5	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

■ Lighting Color

- Blue

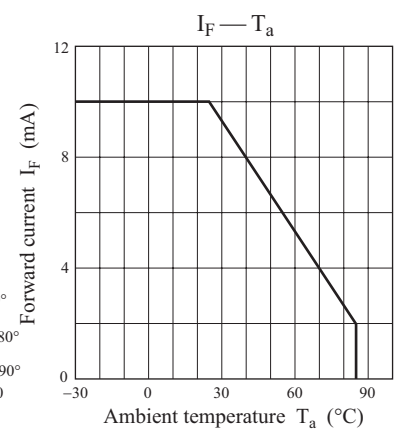
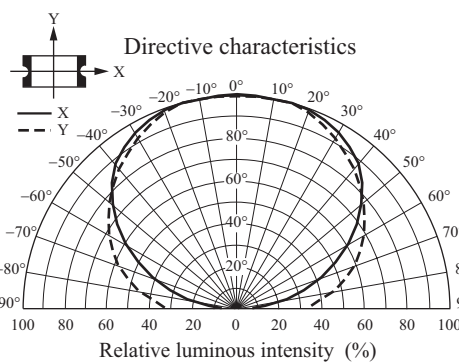
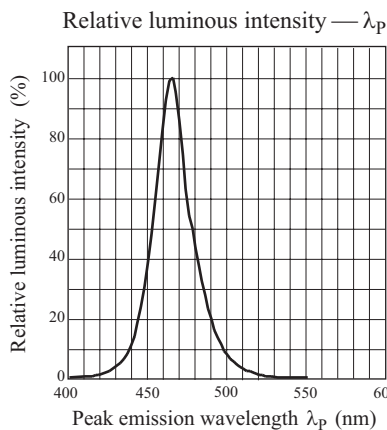
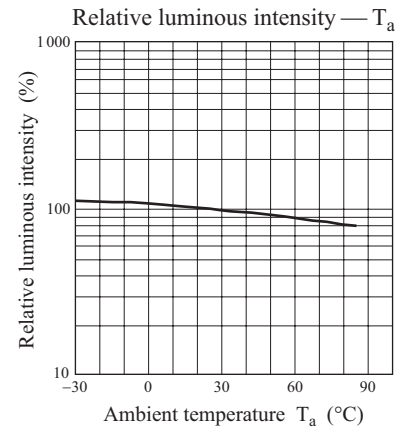
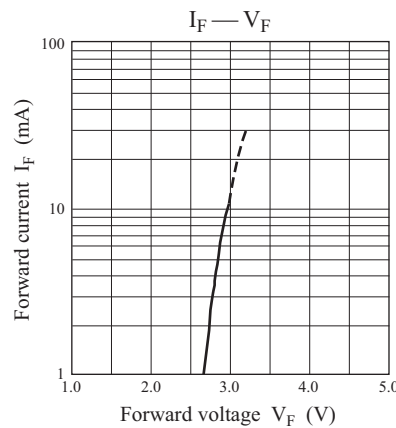
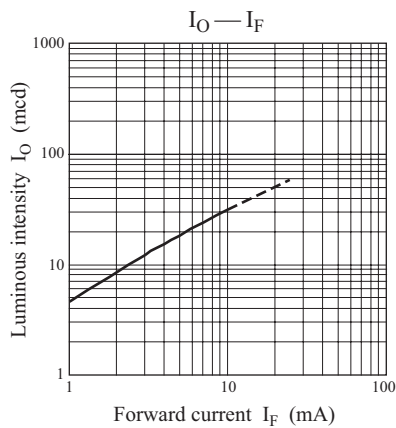
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

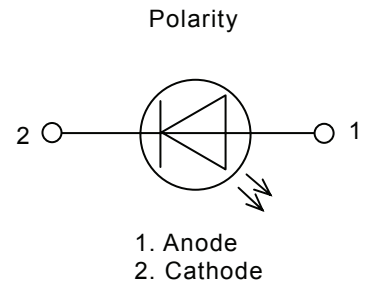
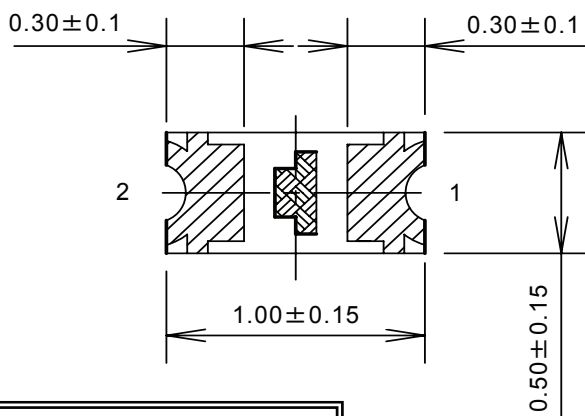
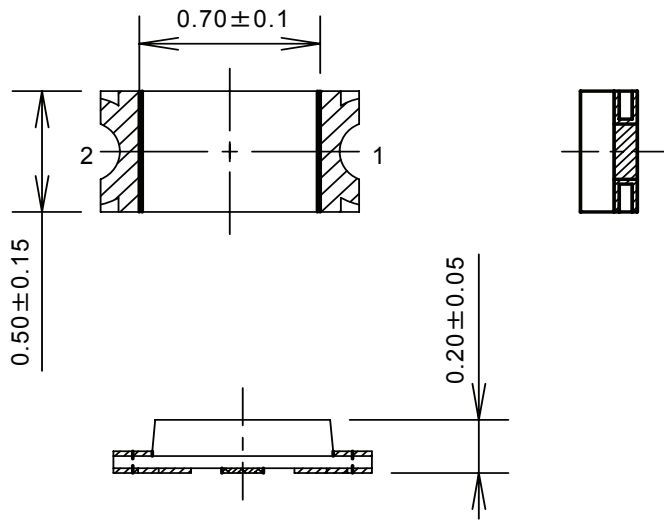
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	I_O	$I_F = 5 \text{ mA}$	8.5	18.0	55.0	mcd
Reverse current	I_R	$V_R = 5 \text{ V}$			10	μA
Forward voltage	V_F	$I_F = 5 \text{ mA}$		2.90	3.20	V
Peak emission wavelength	λ_p	$I_F = 5 \text{ mA}$		465		nm
Dominant emission wavelength *2	λ_d	$I_F = 5 \text{ mA}$	467	472	478	nm
Spectral half band width	$\Delta\lambda$	$I_F = 5 \text{ mA}$		20		nm

Note) *1: Measurement tolerance: $\pm 20\%$

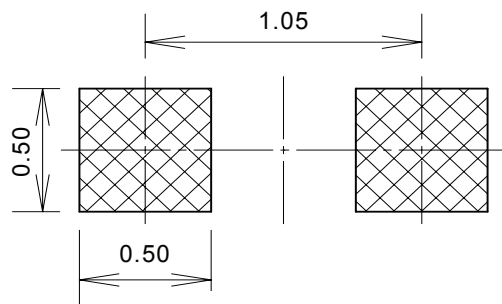
*2: Measurement tolerance: $\pm 2 \text{ nm}$



■ Package (Unit: mm)



Recommended Land Layout



(Note1) Electrode projection is not included in the package dimensions.

(Note2) About solder thickness, please examine the products yourself completely.

(Recommended thickness : $t=0.10$ mm ~ 0.15 mm)

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